

PATENT ABSTRACTS OF JAPAN

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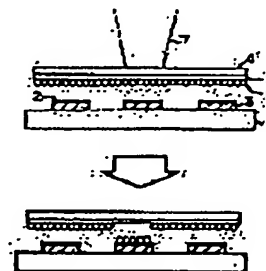
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(54) METHOD AND APPARATUS FOR ARRAYING CONDUCTIVE PARTICLE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method and an apparatus for arraying particles capable of arraying conductive particles on an electrode at high speed and easily, without damaging the particles and without using a method which requires precision work or control of a magnetic film, a metal mask, and so on.

SOLUTION: Relating to a conductive particle arraying method for arraying conductive particles on electrodes, and performing the connection between the electrodes through the above-mentioned conductive particles, conductive particles 6 sticking on a transparent film 4 by a pressure sensitive adhesive 5 are selectively exfoliated by emitting a laser beam 7 on the adhesive surface of the transparent film 4, and the exfoliated conductive particles 6 are transferred and arrayed on the electrodes 3. And, it does not matter if the conductive particles 6 are exfoliated by laser abrasion forming particle patterns on the film, and these particle patterns are transferred and arrayed on the electrodes 3. And a particle arraying apparatus (not shown by a figure) for transferring and arraying conductive particles onto the electrodes provided on boards to be transferred continuously, by the use of the above-mentioned arraying method is constituted.



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